C7403C - C7404C

Conductor

Description

C7403C / C7404C is a ENIG plateable, wire bondable copper conductor system developed for applying thick layers of copper. It is optimized for 96% alumina. It is intended for use where cost sensitive applications involving high thermal and electrical properties are required.C7403C / C7404C are applied by screen printing dried in air and fired in a nitrogen atmosphere C7403C is applied by printing as the base layer. C7404C is printed on top of C7403C to build up to optimal thickness.

Key Features

- Compatible with Al2O3
- Excellent electrical and thermal properties
- Excellent fired film density
- High fired film thickness (up to 300 um) ENIG and ENEPIG plateable
- Wire bondable-thick Al wire

This picture does not show the packaging of C7403C - C7404C and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties	
Viscosity	C7403C: 150 – 250 kcps, C7404C: 150 – 250 kcps-Brookfield HBT, SC4-14 @ 10 rpm, 25°C
Conductivity	≤ 0.8 milliohms/square at 50 um fired film thickness
Alloy Ratio	100

Recommended Processing Guide	
Process Temperature (TDS)	Fire in Nitrogen with O2 between 2-10 ppm 890 ºC peak. Dwell time of 8-10 minutes.

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Warranty

Material guaranteed to meet specifications for 3 months from date of manufacturing with proper storage.

Storage

Store in a dry location at 5 – 25°C. DO NOT REFRIGERATE. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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